











EEE Council on Electronic Design Automation

18th International Forum on MPSoC for Software-defined Hardware July 29 - August 3, 2018, The Cliff Lodge, Snowbird, UT, 84092, USA

FOCUS

Multicore and Multiprocessor SoC (MPSoC) started a new computing era but brought a twofold challenge: building HW easy to use by SW designers and building SW that fully exploits HW

capabilities. The main domains addressed at MPSoC are related to adapting HW and SW for better cost, performances and energy efficiency of next generation computing systems. Emerging SW and HW design technologies and architectures combined with advanced semiconductor manufacturing technologies are explored to build energy efficient multicore architectures serving advanced computing (image, vision and cloud) and distributed networked systems.

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MPSoC is an interdisciplinary forum bringing together key R&D actors from the different fields required to design Multicore and multiprocessor HW and SW

systems. The program brings together experts in major HW and SW architectures (Processor, Memory, I/O, Interconnect, RTOS, GFX, Virtualization, application-(domain) specific acceleration & system architectures), design technologies (parallel programming, rapid prototyping, system design models and tools) and emerging semiconductor technologies (heterogeneous integration, 3D, photonics) to build next-generation thinking that will bridge the gap between HW and SW. Around 60 world class R&D speakers will discuss fundamental and strategic issues to master Software-defined Hardware for energy-efficient and high-performance computing.

The program includes keynotes on major HW and SW trends and technical sessions to present strategic directions and state-of-the-art research. The 5-day program will also include in-depth technology challenge presentations and short keynotes followed by insightful panels. All the talks will be given by CTO-level speakers from Industry and world-class professors from Academia.

WHY ATTEND

Thanks to its full week format and the high quality of both attendees and speakers, MPSoC is a unique opportunity for executives and senior managers to

explore new ideas and refine strategic thinking. MPSoC is **the single best event in the world** that brings together so many leading thinkers on the future of HW and SW design. It enables **great informal networking and interactions** with experienced, distinguished researchers and top academic and industrial experts. It builds **bridges between different technical areas and corporations, institutes and countries.** Finally, it is a unique environment for anyone who wants to share knowledge with researchers and key managers from industry.

FEE

For registration before May 31, the fee amounts to 1400 USD for regular attendees, 1190 USD for IEEE and EDAA members, and 850 USD for speakers. Each speaker is allowed to invite Junior attendee

(student) with a fee of 790 USD. It will cover the documentation, the lunch for five days and dinner for five days including the social dinner.

General Chair:

Pierre-Emmanuel Gaillardon, *University of Utah, USA* **Program Co-Chairs:**

Anca Molnos, CEA-LETI, France Yoshinori Takeuchi, Kindai University, Japan Jishen Zhao, UC San Diego, USA

European Liaison

Frédéric Petrot, TIMA-INP Grenoble, France Nicolas Ventroux, CEA-LIST, France

North American Liaison:

Gabriela Nicolescu, Poly. Montreal, Canada

Asian Liaison:

Shinya Takamaeda-Yamazaki, Hokkaido University, Japan Sungjoo Yoo, Seoul National University, Korea

Industry Liaison:

Andreas Herkersdof, TUM, Germany Yoshifumi Sakamoto, IBM, Japan Yuan Xie, UC Santa Barbara, USA

Local Organization Chair:

Tom Becnel, University of Utah, USA

Finance Chair:

Frédéric Rousseau, TIMA-UGA, France Ken Stevens, University of Utah, USA

Publicity Chair:

Fabien Clermidy, CEA-LETI, France Koji Inoué, Kyuchu University, Japan

Proceedings Chair:

Tom Becnel, University of Utah, USA

Web Chair:

Edouard Giacomin, University of Utah, USA

Technical Program Committee:

Marcello Coppola, STMicroelectronics, France Raphaël David, CEA-List, France Giovanni De Micheli, EPFL, Switzerland

Rolf Ernst, TU Braunschweig, Germany
John Goodgere, APM, UK

John Goodacre, ARM, UK

Kees Goossens, TUE, The Netherlands Masaharu Imai, Osaka University, Japan

Koji Inoue, Kyushu University, Japan Tsuyoshi Isshiki, Tokyo Institute of Tech., Japan

Ahmed Jerraya, CEA-Leti, France

Rainer Leupers, RWTH Aachen University, Germany Youn-long Lin, National Tsing Hua University, Taiwan

Takashi Miyamori, *Toshiba Corp., Japan* Gabriela Nicolescu, *Poly. Montreal, Canada*

Pierre Paulin, *Synopsys, Canada* Frederic Pétrot, *TIMA-INPG, France*

Yoshinori Takeuchi, Kindai University, Japan Hiroyuki Tomiyama, Ritsumeikan University, Japan

Kees Vissers, Xilinx, USA

Norbert Wehn, University of Kaiserslautern, Germany Marilyn Wolf, Georgia Institute of Tech., USA Yuan Xie, UC Santa Barbara, USA

Hiroto Yasuura, Kyushu University, USA

Sungjoo Yoo, Seoul National University, Korea

MPSoC'18 Speakers

KEYNOTES (5)

- Rob Aitken, ARM, UK
- Paul Joyce, Dell EMC, USA
- Ike Nassi, *TidalScale*, *US*
- Shuichi Yamane, Socionext Inc., Japan
- Farhang Yazdani, Broadpak, US

IN-DEPTH PRESENTATIONS (20)

- John Brainbidge, NetSpeed Systems, USA
- Gerhard Fettweis, TU Dresden, Germany
- Masaki Gondo, eSOL Co., Ltd., Japan
- Yoshihiko Hirota, Konica Minolta, Japan
- Masatoshi Ishii, *IBM Research Tokyo, Japan*
- K. Charles Janac, Arteris Inc., USA
- Kerry Kelly, University of Utah, USA
- Shahar Kvatinsky, Technion, Israël
- Peter van der Made, BrainChip Inc., USA
- Takashi Miyamori, Toshiba Corporation, Japan
- Masahiro Murakami, Konica Minolta, Japan
- Yuichi Nakamura, NEC Corp., Japan
- Francois Neumann, Safran Electronics & Defense, France
- Greg Nielson, Nielson Scientific, USA
- Pei-Lin Pai, Winbond, Taiwan
- Pierre Paulin, Synopsys, Canada
- Yankin Tanurhan, Synopsys, USA
- Kees Vissers, Xilinx, USA
- Yuan Xie, UCSB, USA
- Yoshitaka Yaguchi, Konica Minolta, Japan

MINI-KEYNOTES (34)

- Fumio Arakawa, The University of Tokyo, Japan
- Gerd Ascheid, RWTH Aachen University, Germany
- Kees van Berkel, Ericsson, Eindhoven University of Technology, The Netherlands
- Rolf Ernst, Technische Universitat Braunschweig, Germany
- John Goodacre, ARM, UK
- Arnaud Grasset, *Thales Research & Tech.*, France

MINI-KEYNOTES (34)

- Victor Grimblatt, Synopsys Chile R&D Center, Latin America
- Yuko Hara-Azumi, Tokyo Institute of Technology, Japan
- Andreas Herkersdorf, TU Munich, Germany
- Tohru Ishihara, Kyoto University, Japan
- Tsuyoshi Isshiki, Tokyo Institute of Technology, Japan
- Masaaki Kondo, The University of Tokyo, Japan
- Youn-Long Lin, National Tsing Hua University, Taiwan
- Hiroki Matsutani, Keio University, Japan
- Anca Molnos, CEA-Leti, France
- Eric Monchalin, ATOS, France
- Gabriela Nicolescu, Ecole Polytechnique de Montréal, Canada
- Danilo Pau, STMicroelectronics, Italy
- Frédéric Pétrot, TIMA Lab, Grenoble University, France
- Frédéric Rousseau, TIMA Lab, Grenoble University, France
- Yoshifumi Sakamoto, IBM Japan, Japan
- Tsuyoshi Sato, Pioneer, Japan
- Akihiko Shinya, NTT Nanophotonics Center, Japan
- Shinya Takamaeda, Hokkaido University, Japan
- Yoshinori Takeuchi, Kindai University, Japan
- Ittetsu Taniguchi, Graduate School of Information Science and Technology Osaka University, Japan
- Nicolas Ventroux, CEA-List, France
- Norbert Wehn, University of Kaiserslautern, Germany
- Marilyn Wolf, Georgia Tech, USA
- Jiang Xu, Hong Kong University of Science and Technology, Hong Kong
- Song Yao, DeePhi Tech, China
- Sungjoo Yoo, Seoul National University, Korea
- Wei Zhang, Hong Kong University of Science and Technology, Hong Kong
- Jishen Zhao, UCSD, USA

Total speakers: 59

MPSoC'18 FORUM REGISTRATION FORM

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Please mail or fax this form to: MPSOC'18 – MP Associates Inc., 1721 Boulder St. Ste. 107, Louisville, CO 80027 - USA Tel: +1 (303) 530-4562 Fax: +1 (303) 530-4334 First Name _____ Last Name _____ Company ______City______State _____ Zip _____ Address _____ Country Phone Fax Email Advance registration (before May 31, 2018) – Circle your choice(s) Student/Junior Speaker 850 USD Regular attendee IEEE/EDAA member 2 Days 1400 USD 790 USD 850 USD 850 USD 1190 USD TOTAL FEES _____USD For 2 days only, please circle your choice: **Sun/Mon** Mon/Tue Tue/Wed Wed/Thu Thu/Fri Send full payment in U.S. dollars with this form. Use a check drawn on a US bank or a major credit card. For payments from non-U.S. banks the attendee will be charged a collection fee of US \$30.00. Purchase orders are not accepted. Use your credit card if registering by fax. Make U.S. checks payable to MPSoC. Form of payment: Check Credit card Visa Mastercard American Express Card # Exp. Name (as it appears on card) Signature

Refunds:

Requests for refunds received before May 31, 2018 will be subjected to a \$50 processing fee. No refunds will be made for cancellations received after May 31, 2018 and all registration fees will be forfeited. Register early to avoid disappointment.

MPSoC'18 HOTEL BOOKING



MPSoC'18 will be held in Snowbird, UT, USA From July 29 to August 3, 2018

The Cliff Lodge 9320 South Cliff Lodge Dr Snowbird, UT, 84092, USA

Further information is available at: http://www.mpsoc-forum.org/